



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	11/11/2014
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD80N6F6	TXDP*7D6GAC2	A	SH1A	11/11/2014
Amount		UoM	Unit type	ST ECOPACK Grade
364.00		mg	Each	ECOPACK® 1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	6.5X6.1X2.3	3	gull wing	
Comment	Package: TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TXDP*7D6GAC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	6.833	mg	supplier	die	Silicon (Si)	7440-21-3		6.572	mg	961803	18055
				supplier	metallization	Aluminium (Al)	7429-90-5		0.147	mg	21513	404
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.041	mg	6000	113
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	440	8
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.018	mg	2634	49
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.052	mg	7610	143
Leadframe	Copper & its alloys	160.58	mg	supplier	alloy	Copper (Cu)	7440-50-8		160.273	mg	998088	440310
				supplier	alloy	Iron (Fe)	7439-89-6		0.16	mg	996	440
				supplier	alloy	Iron Phosphide (Fe2P)	1310-43-6		0.048	mg	299	132
				supplier	metallization	Nickel (Ni)	7440-02-0		0.092	mg	573	253
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	44	19
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	44	19
Soft solder	Other Organic Materials	4.91	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.689	mg	954990	12882
				supplier	solder	Silver (Ag)	7440-22-4		0.123	mg	25051	338
				supplier	solder	Tin (Sn)	7440-31-5		0.098	mg	19959	269
Bonding wire	Other inorganic materials	1.647	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.647	mg	1000000	4525
				supplier	wire	Aluminium (Al)	7429-90-5		1.647	mg	1000000	4525
Encapsulation	Other Organic Materials	188.985	mg	supplier	mold compound	Silica, vitreous	60676-86-0		151.188	mg	800000	415352
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		13.229	mg	70000	36343
				supplier	mold compound	Phenol resin	9003-35-4		7.559	mg	39998	20766
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		11.339	mg	59999	31151
				supplier	mold compound	Antimony Trioxide	1309-64-4		2.268	mg	12001	6231
				JIG I	mold compound	Brominated Epoxy Resin	40039-93-8		2.835	mg	15001	7788
				supplier	mold compound	Carbon black	1333-86-4		0.567	mg	3001	1558
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	2871
Connecon coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	2871